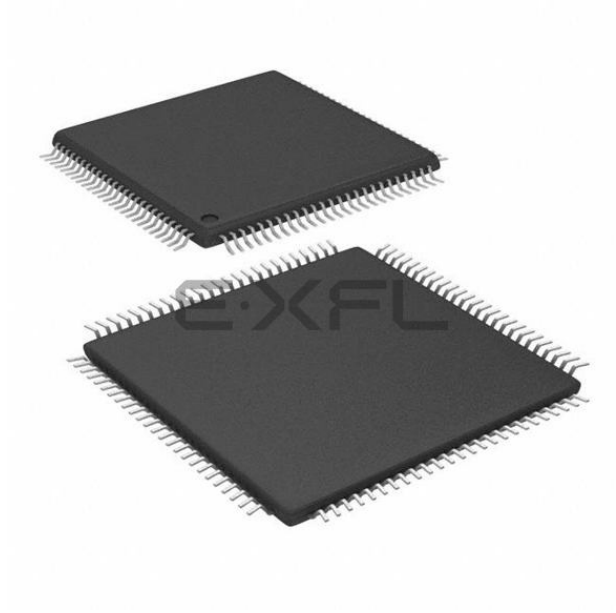
Microchip Technology - DSPIC33FJ128MC510-I/PT Datasheet



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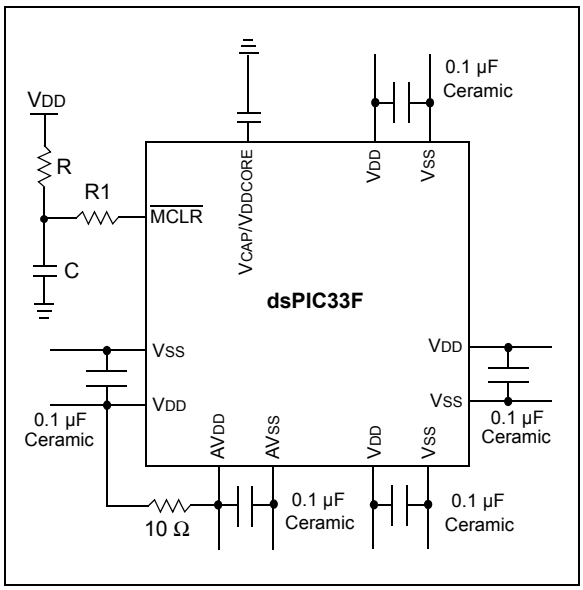
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	85
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj128mc510-i-pt

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 Capacitor on Internal Voltage Regulator (VCAP/VDDCORE)

A low-ESR (< 5 Ohms) capacitor is required on the VCAP/VDDCORE pin, which is used to stabilize the voltage regulator output voltage. The VCAP/VDDCORE pin must not be connected to VDD, and must have a capacitor between 4.7 µF and 10 µF, 16V connected to ground. The type can be ceramic or tantalum. Refer to **Section 26.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP/VDDCORE. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 23.2 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear ($\overline{MCLR}$) Pin

The $\overline{MCLR}$ pin provides for two specific device functions:

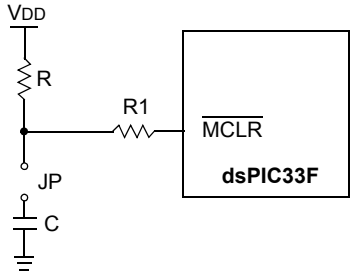
- Device Reset
- Device programming and debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{MCLR}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor C, be isolated from the $\overline{MCLR}$ pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the $\overline{MCLR}$ pin.

FIGURE 2-2: EXAMPLE OF $\overline{MCLR}$ PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{MCLR}$ pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into $\overline{MCLR}$ from the external capacitor C, in the event of $\overline{MCLR}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{MCLR}$ pin VIH and VIL specifications are met.

FIGURE 4-3: DATA MEMORY MAP FOR dsPIC33FJXXXMCX06/X08/X10 DEVICES WITH 8 KBS RAM

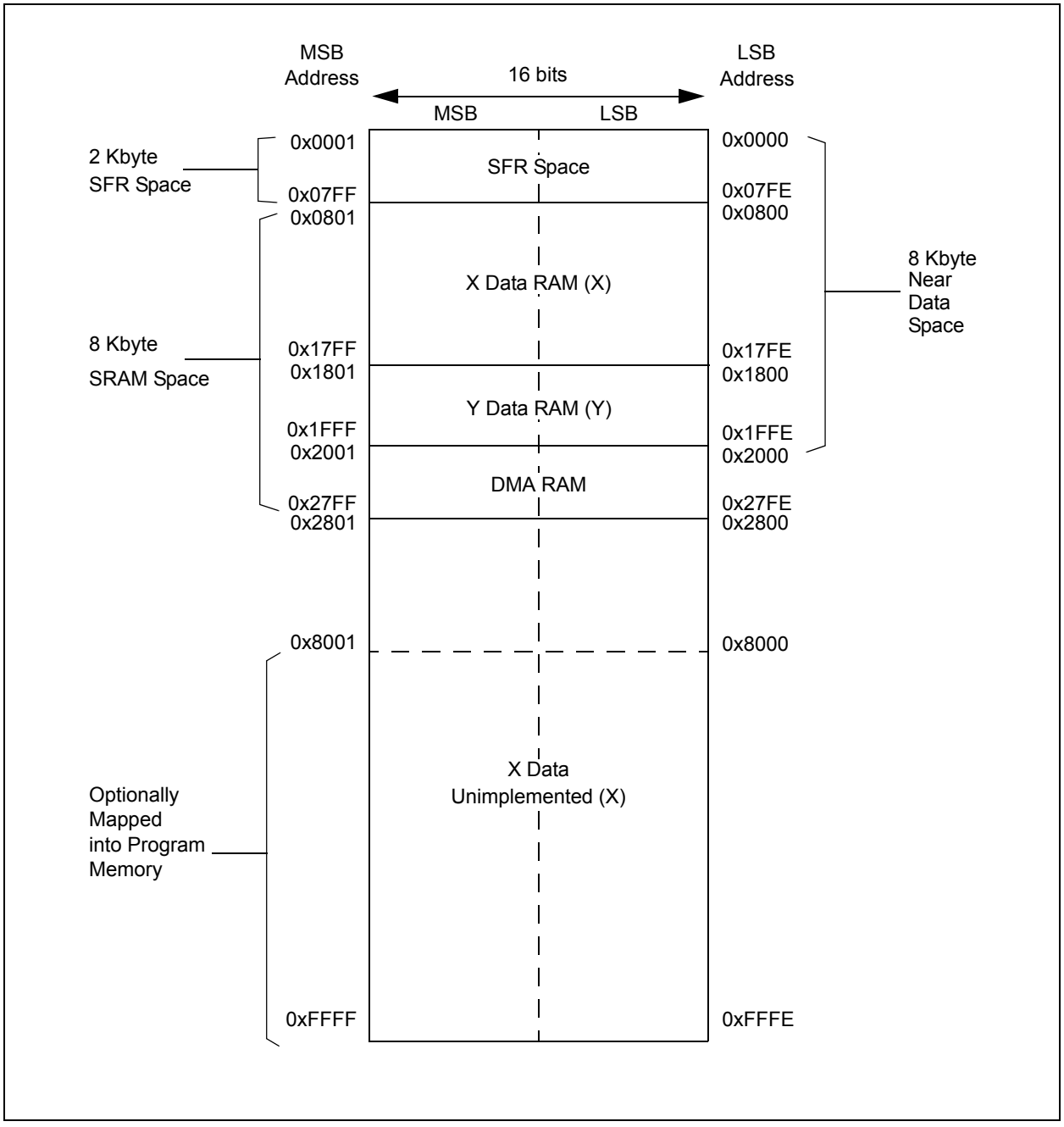


TABLE 4-5: INTERRUPT CONTROLLER REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
INTCON1	0080	NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE	SFTACERR	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—	0000
INTCON2	0082	ALTIVT	DISI	—	—	—	—	—	—	—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
IFS0	0084	—	DMA1IF	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF	T2IF	OC2IF	IC2IF	DMA0IF	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0086	U2TXIF	U2RXIF	INT2IF	T5IF	T4IF	OC4IF	OC3IF	DMA2IF	IC8IF	IC7IF	AD2IF	INT1IF	CNIF	—	MI2C1IF	SI2C1IF	0000
IFS2	0088	T6IF	DMA4IF	—	OC8IF	OC7IF	OC6IF	OC5IF	IC6IF	IC5IF	IC4IF	IC3IF	DMA3IF	C1IF	C1RXIF	SPI2IF	SPI2EIF	0000
IFS3	008A	FLTAIF	—	DMA5IF	—	—	QEIIF	PWMIF	C2IF	C2RXIF	INT4IF	INT3IF	T9IF	T8IF	MI2C2IF	SI2C2IF	T7IF	0000
IFS4	008C	—	—	—	—	—	—	—	—	C2TXIF	C1TXIF	DMA7IF	DMA6IF	—	U2EIF	U1EIF	FLTBIF	0000
IEC0	0094	—	DMA1IE	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE	T2IE	OC2IE	IC2IE	DMA0IE	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0096	U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	OC4IE	OC3IE	DMA2IE	IC8IE	IC7IE	AD2IE	INT1IE	CNIE	—	MI2C1IE	SI2C1IE	0000
IEC2	0098	T6IE	DMA4IE	—	OC8IE	OC7IE	OC6IE	OC5IE	IC6IE	IC5IE	IC4IE	IC3IE	DMA3IE	C1IE	C1RXIE	SPI2IE	SPI2EIE	0000
IEC3	009A	FLTAIE	—	DMA5IE	—	—	QEIIE	PWMIE	C2IE	C2RXIE	INT4IE	INT3IE	T9IE	T8IE	MI2C2IE	SI2C2IE	T7IE	0000
IEC4	009C	—	—	—	—	—	—	—	—	C2TXIE	C1TXIE	DMA7IE	DMA6IE	—	U2EIE	U1EIE	FLTBIE	0000
IPC0	00A4	—	T1IP<2:0>			—	OC1IP<2:0>			—	IC1IP<2:0>			—	INT0IP<2:0>			4444
IPC1	00A6	—	T2IP<2:0>			—	OC2IP<2:0>			—	IC2IP<2:0>			—	DMA0IP<2:0>			4444
IPC2	00A8	—	U1RXIP<2:0>			—	SPI1IP<2:0>			—	SPI1EIP<2:0>			—	T3IP<2:0>			4444
IPC3	00AA	—	—	—	—	—	DMA1IP<2:0>			—	AD1IP<2:0>			—	U1TXIP<2:0>			0444
IPC4	00AC	—	CNIP<2:0>			—	—	—	—	—	MI2C1IP<2:0>			—	SI2C1IP<2:0>			4044
IPC5	00AE	—	IC8IP<2:0>			—	IC7IP<2:0>			—	AD2IP<2:0>			—	INT1IP<2:0>			4444
IPC6	00B0	—	T4IP<2:0>			—	OC4IP<2:0>			—	OC3IP<2:0>			—	DMA2IP<2:0>			4444
IPC7	00B2	—	U2TXIP<2:0>			—	U2RXIP<2:0>			—	INT2IP<2:0>			—	T5IP<2:0>			4444
IPC8	00B4	—	C1IP<2:0>			—	C1RXIP<2:0>			—	SPI2IP<2:0>			—	SPI2EIP<2:0>			4444
IPC9	00B6	—	IC5IP<2:0>			—	IC4IP<2:0>			—	IC3IP<2:0>			—	DMA3IP<2:0>			4444
IPC10	00B8	—	OC7IP<2:0>			—	OC6IP<2:0>			—	OC5IP<2:0>			—	IC6IP<2:0>			4444
IPC11	00BA	—	T6IP<2:0>			—	DMA4IP<2:0>			—	—	—	—	—	OC8IP<2:0>			4404
IPC12	00BC	—	T8IP<2:0>			—	MI2C2IP<2:0>			—	SI2C2IP<2:0>			—	T7IP<2:0>			4444
IPC13	00BE	—	C2RXIP<2:0>			—	INT4IP<2:0>			—	INT3IP<2:0>			—	T9IP<2:0>			4444
IPC14	00C0	—	—	—	—	—	QEIIP<2:0>			—	PWMIP<2:0>			—	C2IP<2:0>			0444
IPC15	00C2	—	FLTAIP<2:0>			—	—	—	—	—	DMA5IP<2:0>			—	—	—	—	4040
IPC16	00C4	—	—	—	—	—	U2EIP<2:0>			—	U1EIP<2:0>			—	FLTBIP<2:0>			0444
IPC17	00C6	—	C2TXIP<2:0>			—	C1TXIP<2:0>			—	DMA7IP<2:0>			—	DMA6IP<2:0>			4444
INTTREG	00E0	—	—	—	—	ILR<3:0>				—	VECNUM<6:0>							0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 6-3: RESET DELAY TIMES FOR VARIOUS DEVICE RESETS

Reset Type	Clock Source	$\overline{\text{SYSRST}}$ Delay	System Clock Delay	FSCM Delay	Notes
POR	EC, FRC, LPRC	TPOR + TSTARTUP + TRST	—	—	**1, 2, 3**
	ECPLL, FRCPLL	TPOR + TSTARTUP + TRST	TLOCK	TFSCM	**1, 2, 3, 5, 6**
	XT, HS, SOSC	TPOR + TSTARTUP + TRST	TOST	TFSCM	**1, 2, 3, 4, 6**
	XTPLL, HSPLL	TPOR + TSTARTUP + TRST	TOST + TLOCK	TFSCM	**1, 2, 3, 4, 5, 6**
BOR	EC, FRC, LPRC	TSTARTUP + TRST	—	—	**3**
	ECPLL, FRCPLL	TSTARTUP + TRST	TLOCK	TFSCM	**3, 5, 6**
	XT, HS, SOSC	TSTARTUP + TRST	TOST	TFSCM	**3, 4, 6**
	XTPLL, HSPLL	TSTARTUP + TRST	TOST + TLOCK	TFSCM	**3, 4, 5, 6**
$\overline{\text{MCLR}}$	Any Clock	TRST	—	—	**3**
WDT	Any Clock	TRST	—	—	**3**
Software	Any Clock	TRST	—	—	**3**
Illegal Opcode	Any Clock	TRST	—	—	**3**
Uninitialized W	Any Clock	TRST	—	—	**3**
Trap Conflict	Any Clock	TRST	—	—	**3**

Note 1: TPOR = Power-on Reset delay (10 μs nominal).

2: TSTARTUP = Conditional POR delay of 20 μs nominal (if on-chip regulator is enabled) or 64 ms nominal Power-up Timer delay (if regulator is disabled). TSTARTUP is also applied to all returns from powered-down states, including waking from Sleep mode, if the regulator is enabled.

3: TRST = Internal state Reset time (20 μs nominal).

4: TOST = Oscillator Start-up Timer. A 10-bit counter counts 1024 oscillator periods before releasing the oscillator clock to the system.

5: TLOCK = PLL lock time (20 μs nominal).

6: TFSCM = Fail-Safe Clock Monitor delay (100 μs nominal).

6.2.1 POR AND LONG OSCILLATOR START-UP TIMES

The oscillator start-up circuitry and its associated delay timers are not linked to the device Reset delays that occur at power-up. Some crystal circuits (especially low-frequency crystals) have a relatively long start-up time. Therefore, one or more of the following conditions is possible after $\overline{\text{SYSRST}}$ is released:

- The oscillator circuit has not begun to oscillate.
- The Oscillator Start-up Timer has not expired (if a crystal oscillator is used).
- The PLL has not achieved a lock (if PLL is used).

The device will not begin to execute code until a valid clock source has been released to the system. Therefore, the oscillator and PLL start-up delays must be considered when the Reset delay time must be known.

6.2.2 FAIL-SAFE CLOCK MONITOR (FSCM) AND DEVICE RESETS

If the FSCM is enabled, it begins to monitor the system clock source when $\overline{\text{SYSRST}}$ is released. If a valid clock source is not available at this time, the device automatically switches to the FRC oscillator and the user can switch to the desired crystal oscillator in the Trap Service Routine.

6.2.2.1 FSCM Delay for Crystal and PLL Clock Sources

When the system clock source is provided by a crystal oscillator and/or the PLL, a small delay, TFSCM, is automatically inserted after the POR and PWRT delay times. The FSCM does not begin to monitor the system clock source until this delay expires. The FSCM delay time is nominally 500 μs and provides additional time for the oscillator and/or PLL to stabilize. In most cases, the FSCM delay prevents an oscillator failure trap at a device Reset when the PWRT is disabled.

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
ALTIVT	DISI	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ALTIVT:** Enable Alternate Interrupt Vector Table bit
1 = Use alternate vector table
0 = Use standard (default) vector table

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13-5 **Unimplemented:** Read as '0'

bit 4 **INT4EP:** External Interrupt 4 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 3 **INT3EP:** External Interrupt 3 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

10.0 POWER-SAVING FEATURES

Note: This data sheet summarizes the features of the dsPIC33FJXXXMCX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog Timer and Power-Saving Modes"** (DS70196) in the *"dsPIC33F Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The dsPIC33FJXXXMCX06/X08/X10 devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. dsPIC33FJXXXMCX06/X08/X10 devices can manage power consumption in four different ways:

- Clock frequency
- Instruction-based Sleep and Idle modes
- Software-controlled Doze mode
- Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

dsPIC33FJXXXMCX06/X08/X10 devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

dsPIC33FJXXXMCX06/X08/X10 devices have two special power-saving modes that are entered through the execution of a special `PWRSAV` instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembly syntax of the `PWRSAV` instruction is shown in Example 10-1.

Note: `SLEEP_MODE` and `IDLE_MODE` are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

10.2.1 SLEEP MODE

Sleep mode has the following features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled.
- The LPRC clock continues to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals may continue to operate in Sleep mode. This includes items such as the input change notification on the I/O ports and peripherals that use an external clock input. Any peripheral that requires the system clock source for its operation is disabled in Sleep mode.

The device will wake-up from Sleep mode on any of the following events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 10-1: `PWRSAV` INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into SLEEP mode
PWRSAV  #IDLE_MODE     ; Put the device into IDLE mode
```

REGISTER 16-4: PxSECMP: SPECIAL EVENT COMPARE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTDIR(1)	SEVTCMP<14:8>(2)						
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTCMP<7:0>(2)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **SEVTDIR:** Special Event Trigger Time Base Direction bit(1)
1 = A Special Event Trigger will occur when the PWM time base is counting downwards
0 = A Special Event Trigger will occur when the PWM time base is counting upwards

bit 14-0 **SEVTCMP<14:0>:** Special Event Compare Value bits(2)

Note 1: SEVTDIR is compared with PTDIR (PTMR<15>) to generate the Special Event Trigger.

2: SEVTCMP<14:0> is compared with PTMR<14:0> to generate the Special Event Trigger.

18.0 SERIAL PERIPHERAL INTERFACE (SPI)

Note: This data sheet summarizes the features of the dsPIC33FJXXXMCX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 18. "Serial Peripheral Interface (SPI)"** (DS70206) in the *"dsPIC33F Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The Serial Peripheral Interface (SPI) module is a synchronous serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, ADC, etc. The SPI module is compatible with SPI and SIOP from Motorola®.

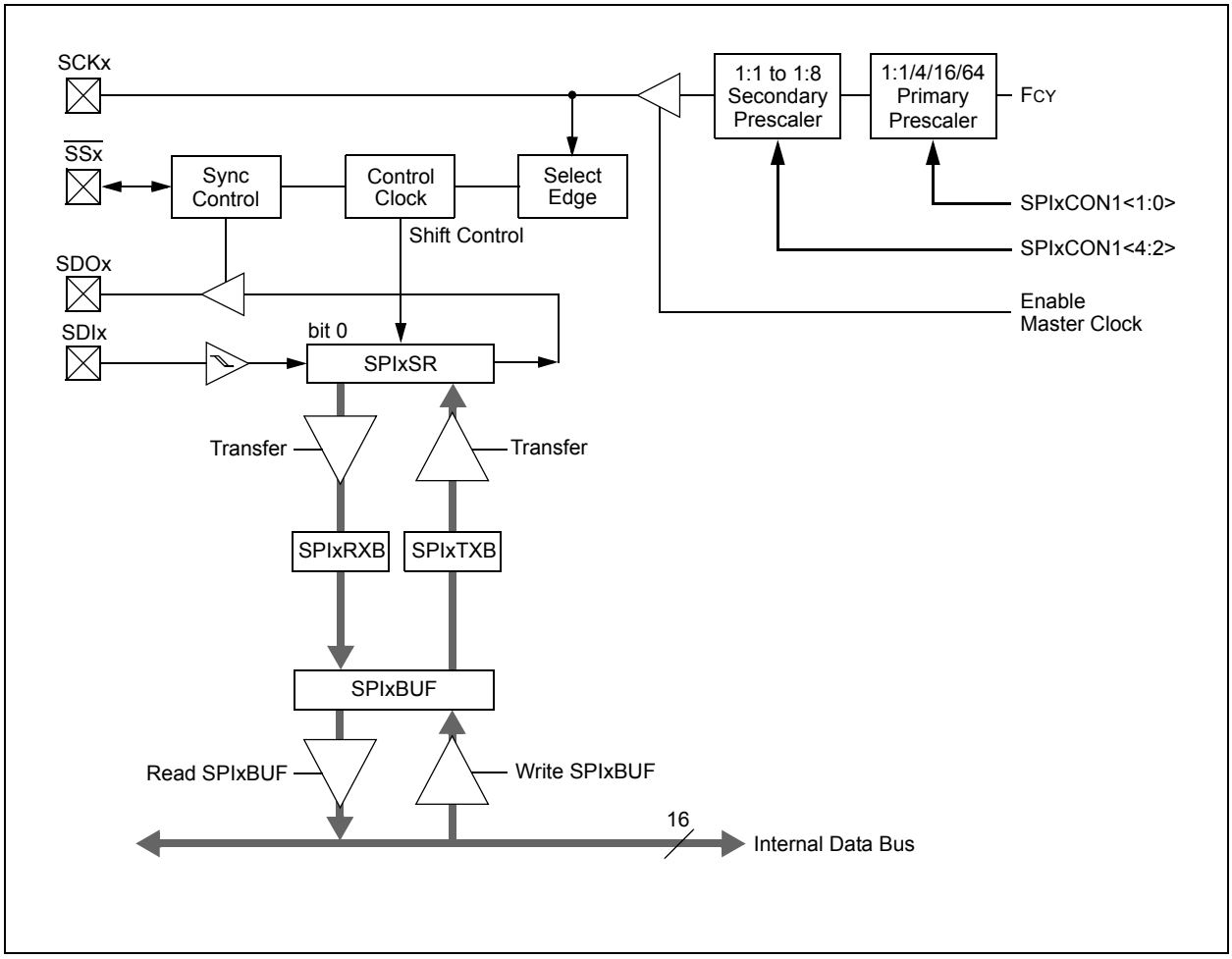
Note: In this section, the SPI modules are referred to together as SPIx, or separately as SPI1 and SPI2. Special Function Registers will follow a similar notation. For example, SPIxCON refers to the control register for the SPI1 or SPI2 module.

Each SPI module consists of a 16-bit shift register, SPIxSR (where x = 1 or 2), used for shifting data in and out, and a buffer register, SPIxBUF. A control register, SPIxCON, configures the module. Additionally, a status register, SPIxSTAT, indicates various status conditions.

The serial interface consists of 4 pins: SDIx (serial data input), SDOx (serial data output), SCKx (shift clock input or output) and $\overline{SSx}$ (active-low slave select).

In Master mode operation, SCK is a clock output, but in Slave mode, it is a clock input.

FIGURE 18-1: SPI MODULE BLOCK DIAGRAM



19.0 INTER-INTEGRATED CIRCUIT™ (I^2C™)

Note: This data sheet summarizes the features of the dsPIC33FJXXXMCX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 19. "Inter-Integrated Circuit™ (I^2C™)"** (DS70195) in the *"dsPIC33F Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The Inter-Integrated Circuit (I^2C) module, with its 16-bit interface, provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard.

The dsPIC33FJXXXMCX06/X08/X10 devices have up to two I^2C interface modules, denoted as I2C1 and I2C2. Each I^2C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I^2C module 'x' (x = 1 or 2) offers the following key features:

- I^2C interface supports both master and slave operation.
- I^2C Slave mode supports 7- and 10-bit addresses.
- I^2C Master mode supports 7- and 10-bit addresses.
- I^2C Port allows bidirectional transfers between master and slaves.
- Serial clock synchronization for the I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control).
- I^2C supports multi-master operation; it detects bus collision and will arbitrate accordingly.

19.1 Operating Modes

The hardware fully implements all the master and slave functions of the I^2C Standard and Fast mode specifications, as well as 7 and 10-bit addressing.

The I^2C module can operate either as a slave or a master on an I^2C bus.

The following types of I^2C operation are supported:

- I^2C slave operation with 7-bit address
- I^2C slave operation with 10-bit address
- I^2C master operation with 7 or 10-bit address

For details about the communication sequence in each of these modes, please refer to the "*dsPIC30F Family Reference Manual*".

19.2 I^2C Registers

I2CxCON and I2CxSTAT are control and status registers, respectively. The I2CxCON register is readable and writable. The lower six bits of I2CxSTAT are read-only. The remaining bits of the I2CSTAT are read/write.

I2CxRSR is the shift register used for shifting data, whereas I2CxRCV is the buffer register to which data bytes are written, or from which data bytes are read. I2CxRCV is the receive buffer. I2CxTRN is the transmit register to which bytes are written during a transmit operation.

The I2CxADD register holds the slave address. A status bit, ADD10, indicates 10-bit Address mode. The I2CxBRG acts as the Baud Rate Generator (BRG) reload value.

In receive operations, I2CxRSR and I2CxRCV together form a double-buffered receiver. When I2CxRSR receives a complete byte, it is transferred to I2CxRCV and an interrupt pulse is generated.

NOTES:

REGISTER 21-10: CiCFG2: ECAN™ BAUD RATE CONFIGURATION REGISTER 2

U-0	R/W-x	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	WAKFIL	—	—	—	SEG2PH<2:0>		
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SEG2PHTS	SAM	SEG1PH<2:0>			PRSEG<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14 **WAKFIL:** Select CAN bus Line Filter for Wake-up bit
1 = Use CAN bus line filter for wake-up
0 = CAN bus line filter is not used for wake-up

bit 13-11 **Unimplemented:** Read as '0'

bit 10-8 **SEG2PH<2:0>:** Phase Buffer Segment 2 bits
111 = Length is 8 x TQ
000 = Length is 1 x TQ

bit 7 **SEG2PHTS:** Phase Segment 2 Time Select bit
1 = Freely programmable
0 = Maximum of SEG1PH bits or Information Processing Time (IPT), whichever is greater

bit 6 **SAM:** Sample of the CAN bus Line bit
1 = Bus line is sampled three times at the sample point
0 = Bus line is sampled once at the sample point

bit 5-3 **SEG1PH<2:0>:** Phase Buffer Segment 1 bits
111 = Length is 8 x TQ
000 = Length is 1 x TQ

bit 2-0 **PRSEG<2:0>:** Propagation Time Segment bits
111 = Length is 8 x TQ
000 = Length is 1 x TQ

REGISTER 21-15: CiBUFPNT4: ECAN™ FILTER 12-15 BUFFER POINTER REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15BP<3:0>				F14BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F13BP<3:0>				F12BP<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **F15BP<3:0>:** RX Buffer Written when Filter 15 Hits bits

bit 11-8 **F14BP<3:0>:** RX Buffer Written when Filter 14 Hits bits

bit 7-4 **F13BP<3:0>:** RX Buffer Written when Filter 13 Hits bits

bit 3-0 **F12BP<3:0>:** RX Buffer Written when Filter 12 Hits bits

REGISTER 21-20: CiRXMnSID: ECAN™ ACCEPTANCE FILTER MASK n STANDARD IDENTIFIER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID2	SID1	SID0	—	MIDE	—	EID17	EID16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **SID<10:0>:** Standard Identifier bits
1 = Include bit SIDx in filter comparison
0 = Bit SIDx is don't care in filter comparison

bit 4 **Unimplemented:** Read as '0'

bit 3 **MIDE:** Identifier Receive Mode bit
1 = Match only message types (standard or extended address) that correspond to EXIDE bit in filter
0 = Match either standard or extended address message if filters match
(i.e., if (Filter SID) = (Message SID) or if (Filter SID/EID) = (Message SID/EID))

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **EID<17:16>:** Extended Identifier bits
1 = Include bit EIDx in filter comparison
0 = Bit EIDx is don't care in filter comparison

REGISTER 21-21: CiRXMnEID: ECAN™ ACCEPTANCE FILTER MASK n EXTENDED IDENTIFIER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID15	EID14	EID13	EID12	EID11	EID10	EID9	EID8
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID7	EID6	EID5	EID4	EID3	EID2	EID1	EID0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **EID<15:0>:** Extended Identifier bits
1 = Include bit EIDx in filter comparison
0 = Bit EIDx is don't care in filter comparison

TABLE 24-2: INSTRUCTION SET OVERVIEW

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
1	ADD	ADD	Acc	Add Accumulators	1	1	OA,OB,SA,SB
		ADD	f	f = f + WREG	1	1	C,DC,N,OV,Z
		ADD	f,WREG	WREG = f + WREG	1	1	C,DC,N,OV,Z
		ADD	#lit10,Wn	Wd = lit10 + Wd	1	1	C,DC,N,OV,Z
		ADD	Wb,Ws,Wd	Wd = Wb + Ws	1	1	C,DC,N,OV,Z
		ADD	Wb,#lit5,Wd	Wd = Wb + lit5	1	1	C,DC,N,OV,Z
		ADD	Wso,#Slit4,Acc	16-bit Signed Add to Accumulator	1	1	OA,OB,SA,SB
2	ADDC	ADDC	f	f = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	f,WREG	WREG = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	#lit10,Wn	Wd = lit10 + Wd + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,Ws,Wd	Wd = Wb + Ws + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,#lit5,Wd	Wd = Wb + lit5 + (C)	1	1	C,DC,N,OV,Z
3	AND	AND	f	f = f .AND. WREG	1	1	N,Z
		AND	f,WREG	WREG = f .AND. WREG	1	1	N,Z
		AND	#lit10,Wn	Wd = lit10 .AND. Wd	1	1	N,Z
		AND	Wb,Ws,Wd	Wd = Wb .AND. Ws	1	1	N,Z
		AND	Wb,#lit5,Wd	Wd = Wb .AND. lit5	1	1	N,Z
4	ASR	ASR	f	f = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	f,WREG	WREG = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	Ws,Wd	Wd = Arithmetic Right Shift Ws	1	1	C,N,OV,Z
		ASR	Wb,Wns,Wnd	Wnd = Arithmetic Right Shift Wb by Wns	1	1	N,Z
		ASR	Wb,#lit5,Wnd	Wnd = Arithmetic Right Shift Wb by lit5	1	1	N,Z
5	BCLR	BCLR	f,#bit4	Bit Clear f	1	1	None
		BCLR	Ws,#bit4	Bit Clear Ws	1	1	None
6	BRA	BRA	C,Expr	Branch if Carry	1	1 (2)	None
		BRA	GE,Expr	Branch if greater than or equal	1	1 (2)	None
		BRA	GEU,Expr	Branch if unsigned greater than or equal	1	1 (2)	None
		BRA	GT,Expr	Branch if greater than	1	1 (2)	None
		BRA	GTU,Expr	Branch if unsigned greater than	1	1 (2)	None
		BRA	LE,Expr	Branch if less than or equal	1	1 (2)	None
		BRA	LEU,Expr	Branch if unsigned less than or equal	1	1 (2)	None
		BRA	LT,Expr	Branch if less than	1	1 (2)	None
		BRA	LTU,Expr	Branch if unsigned less than	1	1 (2)	None
		BRA	N,Expr	Branch if Negative	1	1 (2)	None
		BRA	NC,Expr	Branch if Not Carry	1	1 (2)	None
		BRA	NN,Expr	Branch if Not Negative	1	1 (2)	None
		BRA	NOV,Expr	Branch if Not Overflow	1	1 (2)	None
		BRA	NZ,Expr	Branch if Not Zero	1	1 (2)	None
		BRA	OA,Expr	Branch if Accumulator A overflow	1	1 (2)	None
		BRA	OB,Expr	Branch if Accumulator B overflow	1	1 (2)	None
		BRA	OV,Expr	Branch if Overflow	1	1 (2)	None
		BRA	SA,Expr	Branch if Accumulator A saturated	1	1 (2)	None
		BRA	SB,Expr	Branch if Accumulator B saturated	1	1 (2)	None
		BRA	Expr	Branch Unconditionally	1	2	None
		BRA	Z,Expr	Branch if Zero	1	1 (2)	None
		BRA	Wn	Computed Branch	1	2	None
7	BSET	BSET	f,#bit4	Bit Set f	1	1	None
		BSET	Ws,#bit4	Bit Set Ws	1	1	None
8	BSW	BSW.C	Ws,Wb	Write C bit to Ws<Wb>	1	1	None
		BSW.Z	Ws,Wb	Write Z bit to Ws<Wb>	1	1	None
9	BTG	BTG	f,#bit4	Bit Toggle f	1	1	None
		BTG	Ws,#bit4	Bit Toggle Ws	1	1	None

25.7 MPLAB ICE 2000 High-Performance In-Circuit Emulator

The MPLAB ICE 2000 In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PIC microcontrollers. Software control of the MPLAB ICE 2000 In-Circuit Emulator is advanced by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The architecture of the MPLAB ICE 2000 In-Circuit Emulator allows expansion to support new PIC microcontrollers.

The MPLAB ICE 2000 In-Circuit Emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft® Windows® 32-bit operating system were chosen to best make these features available in a simple, unified application.

25.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The MPLAB REAL ICE probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with the popular MPLAB ICD 2 system (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

MPLAB REAL ICE is field upgradeable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added, such as software breakpoints and assembly code trace. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, real-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

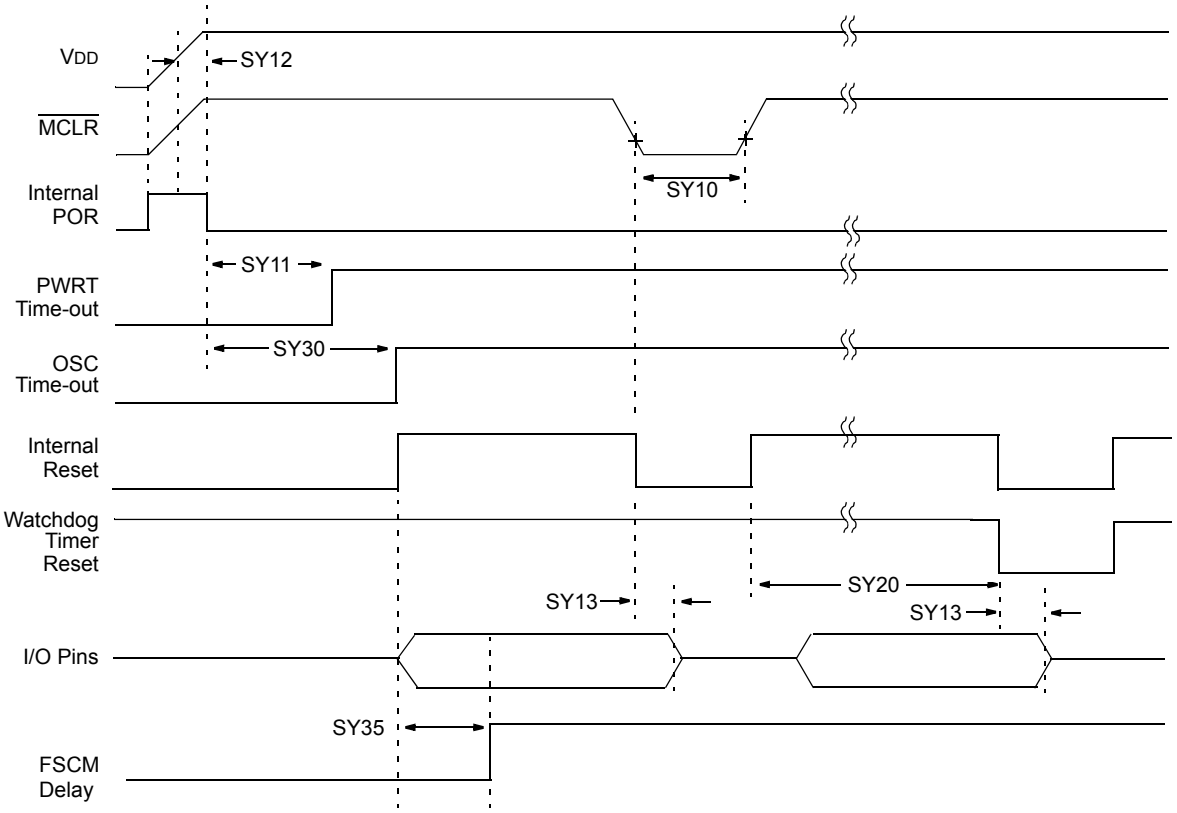
25.9 MPLAB ICD 2 In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD 2, is a powerful, low-cost, run-time development tool, connecting to the host PC via an RS-232 or high-speed USB interface. This tool is based on the Flash PIC MCUs and can be used to develop for these and other PIC MCUs and dsPIC DSCs. The MPLAB ICD 2 utilizes the in-circuit debugging capability built into the Flash devices. This feature, along with Microchip's In-Circuit Serial Programming™ (ICSP™) protocol, offers cost-effective, in-circuit Flash debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by setting breakpoints, single stepping and watching variables, and CPU status and peripheral registers. Running at full speed enables testing hardware and applications in real time. MPLAB ICD 2 also serves as a development programmer for selected PIC devices.

25.10 MPLAB PM3 Device Programmer

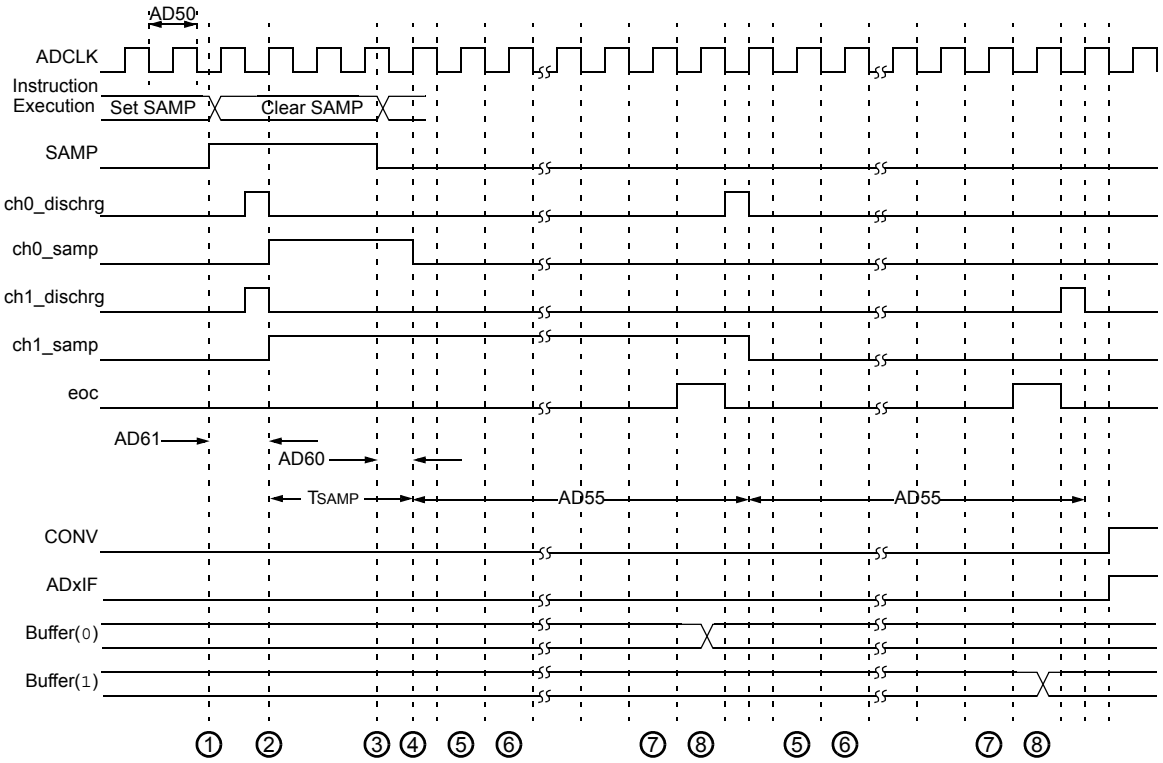
The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an SD/MMC card for file storage and secure data applications.

FIGURE 26-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-24: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000)



(1) – Software sets ADxCON. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F Family Reference Manual"*.

(3) – Software clears ADxCON. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

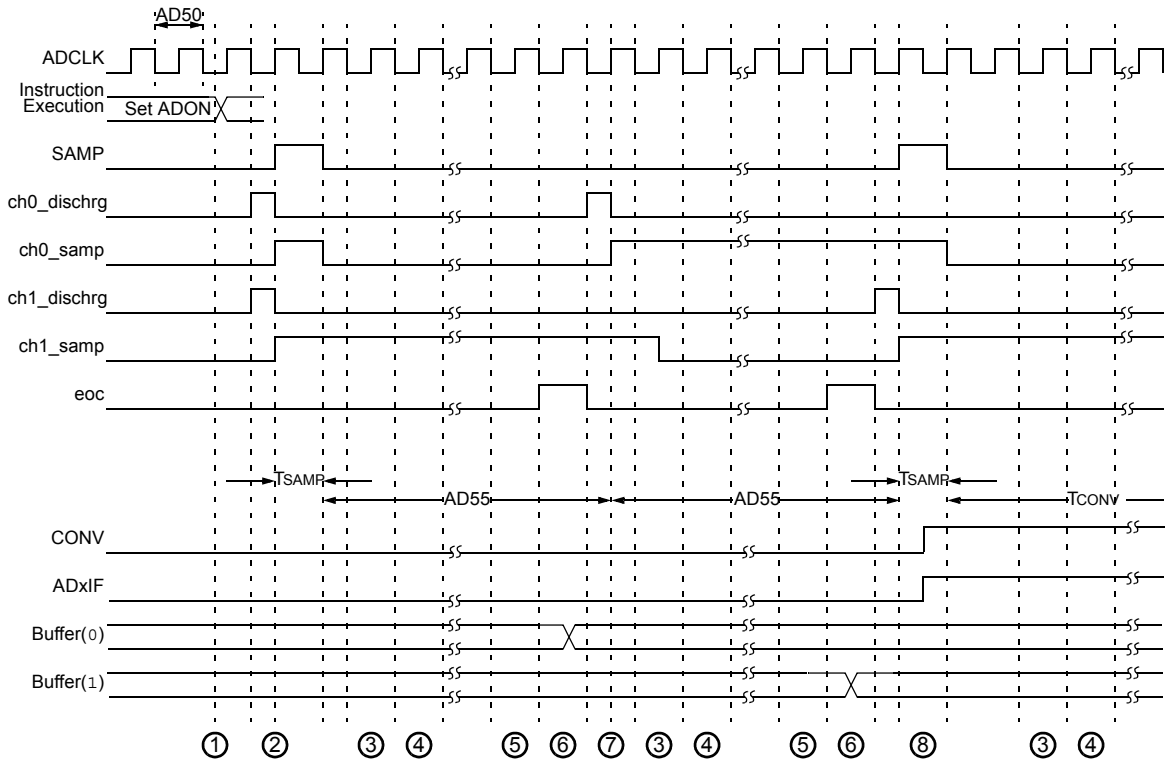
(5) – Convert bit 9.

(6) – Convert bit 8.

(7) – Convert bit 0.

(8) – One TAD for end of conversion.

FIGURE 26-25: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



(1) – Software sets ADxCON. ADON to start AD operation.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F Family Reference Manual"*.

(3) – Convert bit 9.

(4) – Convert bit 8.

(5) – Convert bit 0.

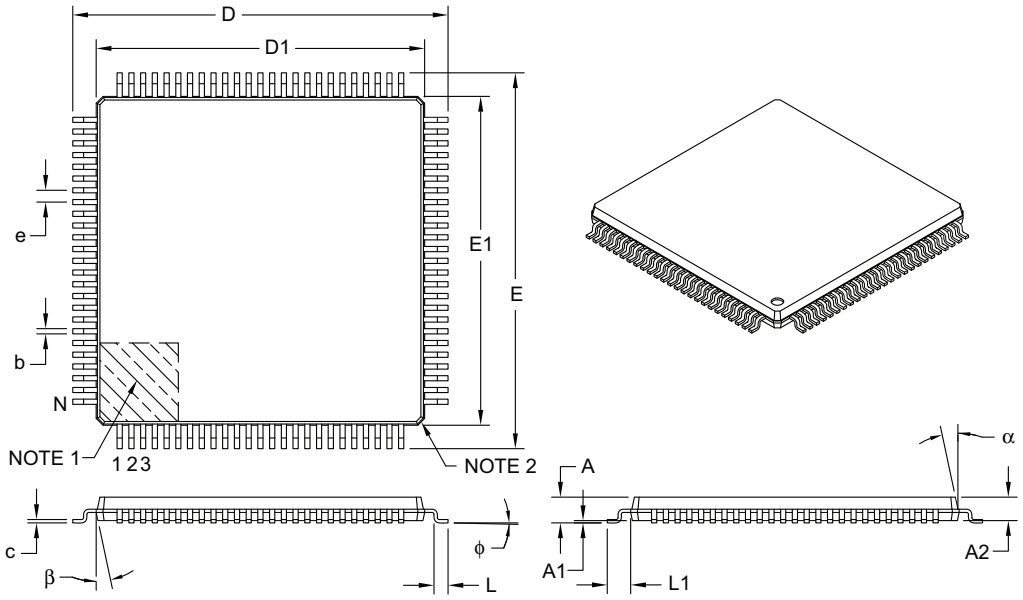
(6) – One TAD for end of conversion.

(7) – Begin conversion of next channel.

(8) – Sample for time specified by SAMC<4:0>.

100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		16.00 BSC	
Overall Length	D		16.00 BSC	
Molded Package Width	E1		14.00 BSC	
Molded Package Length	D1		14.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B

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